

Application No.: 10/036,462

Attorney Docket No.: YO997-211US2  
20140-00216-US2

said electrically conducting adhesive being deposited either on the said electrode pads of the said glass plate or on the said conducting beam leads of a TAB package; and

wherein the said electrically conducting adhesive comprises:

a thermoplastic or thermoset polymer resin matrix,

no-clean solder flux,

a plurality of electrically conducting particles with an electrically conducting fusible coating with at least some of said particles being fused to other said particles through said electrically conductive fusible coating.

### REMARKS

As discussed during a recent telephone discussion with Examiner Williams, claim 32 has been amended to include recitations concerning the adhesive along the lines of those present in claim 3.

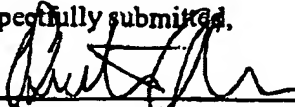
Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to pass this application to issue.

**FAX RECEIVED**

Dated: May 20, 2003  
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Respectfully submitted,

By   
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Attorney Document No.: YO997-211US2  
20140-00216-US2**Version With Markings to Show Changes Made****IN THE CLAIMS:**

Please AMEND claim 32 as follows:

32 Currently Amended) A structure comprising:

a plurality of electrically conducting beam leads in an array on an electronic chip carrier of a TAB package used for electrically connecting between an active matrix liquid crystal display (AMLCD) and a printed circuit board;

said beam leads being electrically and mechanically joined to the electrodes on an AMLCD glass plate by means of an electrically conducting adhesive;

said electrically conducting adhesive being deposited either on the said electrode pads of the said glass plate or on the said conducting beam leads of a TAB package; and

wherein the said electrically conducting adhesive comprises:

a thermoplastic or thermoset polymer resin matrix,

no-clean solder flux,

a plurality of electrically conducting particles with an electrically conducting fusible coating with at least some of said particles being fused to other said particles through said electrically conductive fusible coating.